



FTB1FK THRU FTB10FK

1.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

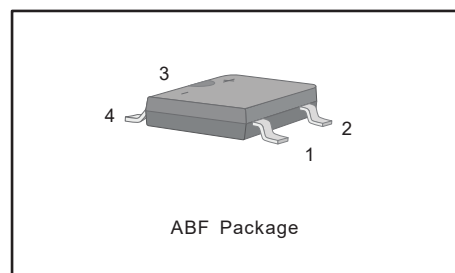
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: ABF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 82mg 0.0029oz

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FTB1FK	FTB2FK	FTB4FK	FTB6FK	FTB8FK	FTB10FK	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^{\circ}\text{C}$	I_O	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Maximum Forward Voltage at 1.0 A	V_F	1.3						V
Maximum DC Reverse Current $T_a = 25\text{ }^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^{\circ}\text{C}$	I_R	5.0 50						μA
Typical Junction Capacitance (Note1)	C_j	13						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	75						$^{\circ}\text{C/W}$
Maximum Reverse Recovery Time (Note3)	t_{rr} $t_{rr(TYP.)}$	500 300						ns
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^{\circ}\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

3. Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $t_{rr} = 0.25\text{ A}$.

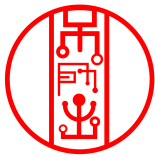


Fig.1 Average Rectified Output Current Derating Curve

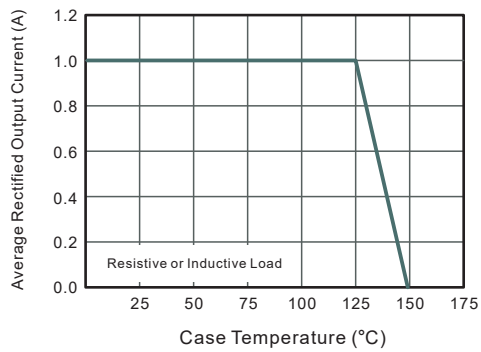


Fig.2 Typical Reverse Characteristics

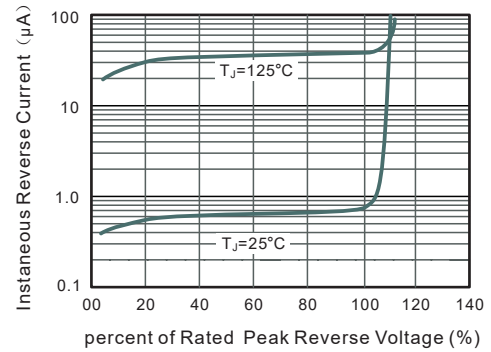


Fig.3 Typical Instantaneous Forward Characteristics

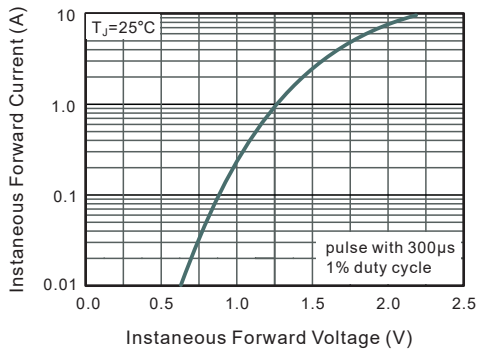


Fig.4 Typical Junction Capacitance

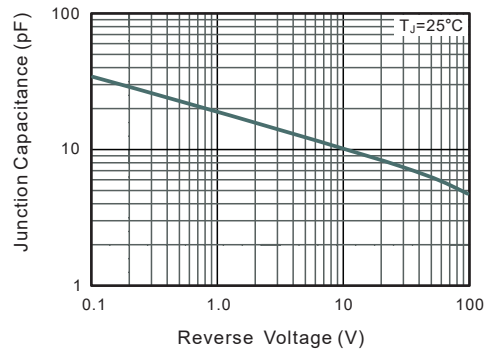
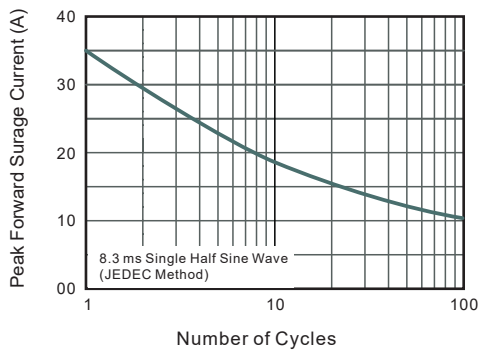


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



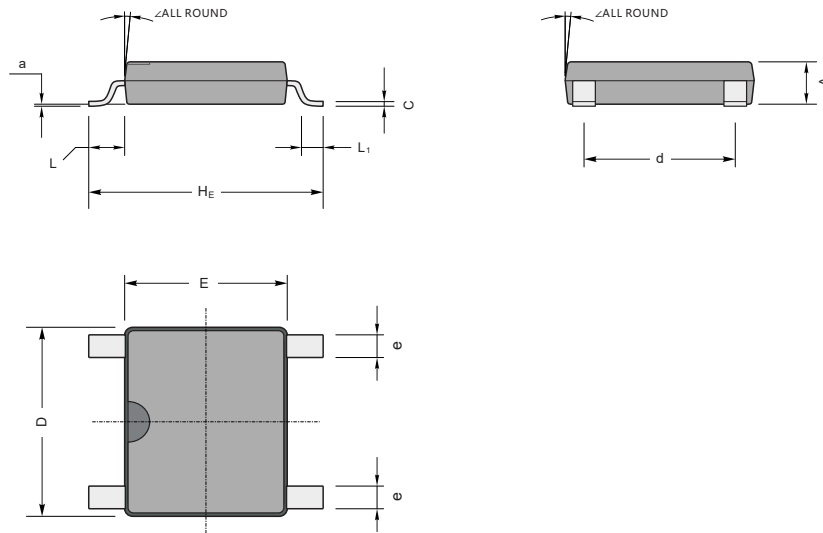


FTB1FK THRU FTB10FK

PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABF



ABF mechanical data

UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.0	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	47	8.7	205	177	252	165	28	37	24	8	
	min	39	5.9	193	166	236	150	20				

The recommended mounting pad size

